

## 20V N-Channel Enhancement Mode MOSFET

### Features

$V_{DS}$  (V) = 20 V

$I_D$  = 2.8 A

$R_{DS(ON)}$  = 60 m $\Omega$  @  $V_{GS}$  = 4.5V

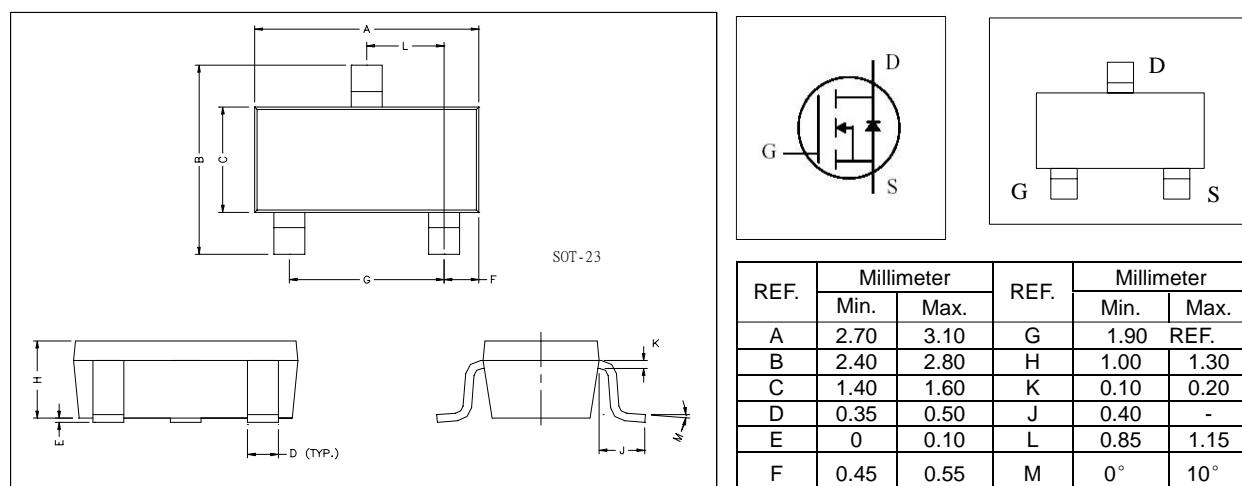
$R_{DS(ON)}$  = 70 m $\Omega$  @  $V_{GS}$  = 2.5V

### Features

Advanced trench process technology

High Density Cell Design For Ultra Low On-Resistance

### Package Dimensions



### Absolute Maximum Ratings @ $T_A$ = 25°C unless otherwise noted

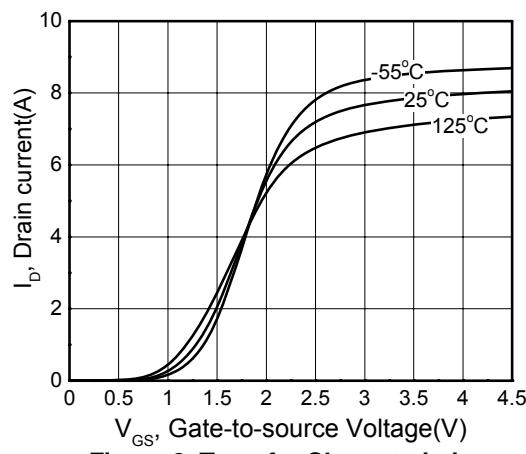
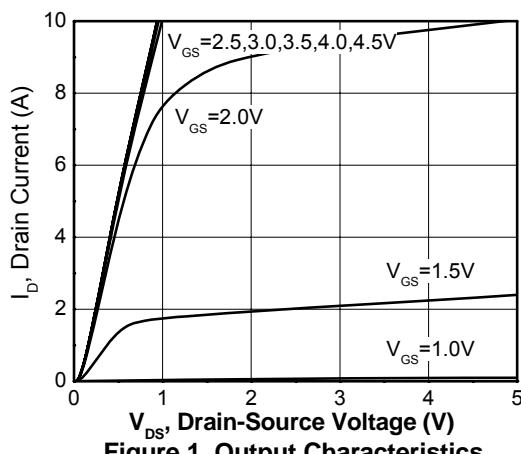
Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	$V_{DSS}$	20	V
Gate-Source Voltage	$V_{GSS}$	$\pm 12$	
Drain Current (Note 1)	$I_D$	2.8	A
Power Dissipation (Note 1)	$P_D$	350	mW
Operating and Storage Temperature Range	$T_J$ , $T_{STG}$	-55 to +150	°C

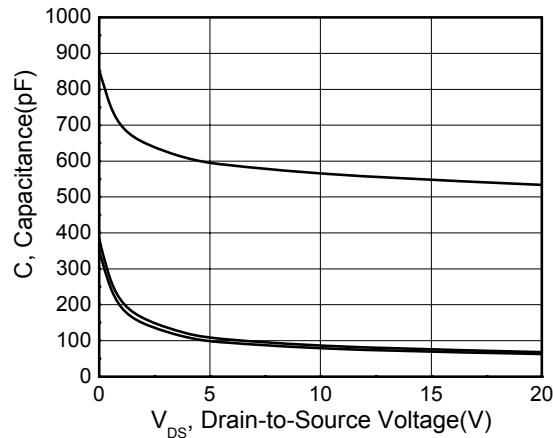
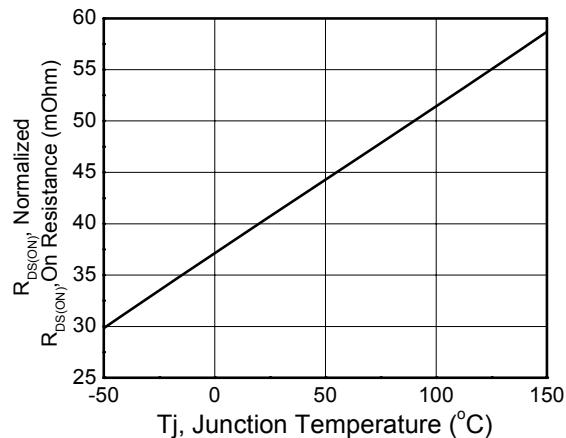
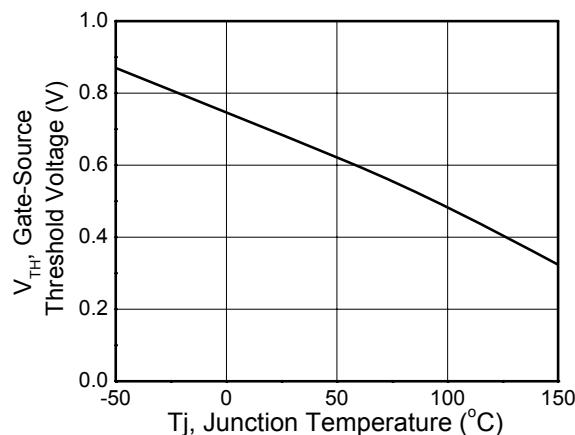
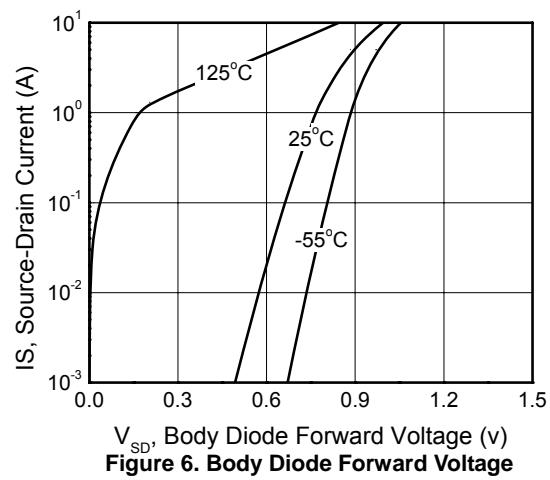
Note: 1. Mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch, for each single die.

**20V N-Channel Enhancement Mode MOSFET**
**Electrical Characteristics @  $T_A = 25^\circ\text{C}$  unless otherwise specified**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS (Note 2)</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	20	25	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	1	$\mu\text{A}$
Gate-Body Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 12\text{V}, V_{\text{DS}} = 0\text{V}$	--	--	$\pm 100$	nA
<b>ON CHARACTERISTICS (Note 2)</b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{TH})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	0.6	0.76	--	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 3\text{A}$	--	60	70	$\text{m}\Omega$
		$V_{\text{GS}} = 2.5\text{V}, I_D = 2\text{A}$	--	70	80	
Forward Transconductance	$G_{\text{FS}}$	$V_{\text{DS}} = 10\text{V}, I_D = 6\text{A}$	--	5	--	S
<b>DYNAMIC CHARACTERISTICS</b>						
Input Capacitance	$C_{\text{ISS}}$	$V_{\text{DS}} = 8\text{V}, V_{\text{GS}} = 0\text{V}$ $F = 1.0\text{MHz}$	--	562	--	$\text{pF}$
Output Capacitance	$C_{\text{OSS}}$		--	106	--	
Reverse Transfer Capacitance	$C_{\text{RSS}}$		--	75	--	
Total Gate Charge	$Q_G$	$V_{\text{DS}} = 10\text{V}, I_D = 6\text{A},$ $V_{\text{GS}} = 4.5\text{V}$	--	4.86	--	$\text{nC}$
Gate-Source Charge	$Q_{\text{GS}}$		--	0.92	--	
Gate-Drain	$Q_{\text{GD}}$		--	1.4	--	
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	$T_{\text{D}(\text{ON})}$	$V_{\text{DD}} = 10\text{V}, I_D = 1\text{A},$ $V_{\text{GEN}} = 4.5\text{V}, R_G = 6\Omega$	--	18	--	$\text{ns}$
Turn-Off Delay Time	$T_{\text{D}(\text{OFF})}$		--	25	--	

Note: 2. Short duration test pulse used to minimize self-heating effect.

**Typical Performance Characteristics**


**20V N-Channel Enhancement Mode MOSFET**

**Figure 3. Capacitance**

**Figure 4. On Resistance Vs. Temperature**

**Figure 5. Gate Thersholt Vs. Temperature**

**Figure 6. Body Diode Forward Voltage**
**Vs. Source Current**